

METHOD FOR PRODUCING WIRING SUBSTRATE

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ABSTRACT OF THE DISCLOSURE

10 A method for producing a wiring substrate provided
with bumps protruding from a surface of the substrate,
the method comprising the steps of: covering one side of
a metallic base with an electrical insulating film and
forming open holes in the insulating film so as to expose
at the bottoms thereof the base, etching the base using
the insulating film having the open holes formed as a
15 mask to form concavities in the base, electroplating the
interior face of each of the concavities using the base
as a plating power supply layer to form a barrier metal
film on the interior face of each concavities, filling
the concavities with a material for the bump by
20 electroplating using the base as a plating power supply
layer, forming a barrier layer on the surface of the
material for the bump filled in each of the concavities
using the base as a plating power supply layer, forming a
stack of a predetermined number of wiring patterns on the
25 insulating film, the adjacent wiring patterns in the
stack being separated from each other by an intervening
insulating layer and being connected to each other
through vias formed in the intervening insulating layer,
and the wiring patterns being electrically connected to
30 the material for the bump filled in the concavities,
removing the base from the stack of wiring patterns
having bumps each having the barrier metal film, and
removing the barrier metal film from each of the bumps.